

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	IPP80N06S4-07	**Issued**	04. May 2021
MA#	MA001055118		
Package	PG-TO220-3-1	**Weight***	2035.91 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.466	0.12	0.12	1211	1211
leadframe	inorganic material	phosphorus	7723-14-0	0.245	0.01		120	
	non noble metal	iron	7439-89-6	0.816	0.04		401	
	non noble metal	copper	7440-50-8	815.335	40.07	40.12	400476	400997
wire	non noble metal	aluminium	7429-90-5	6.739	0.33	0.33	3310	3310
encapsulation	inorganic material	zincoxide	1314-13-2	5.959	0.29		2927	
	miscellaneous	miscellaneous	-	23.838	1.17		11709	
	plastics	epoxy resin	-	89.391	4.39		43907	
	inorganic material	silicondioxide	60676-86-0	476.752	23.42	29.27	234171	292714
leadfinish	non noble metal	tin	7440-31-5	21.462	1.05	1.05	10542	10542
plating	inorganic material	phosphorus	7723-14-0	0.001			1	
	non noble metal	nickel	7440-02-0	0.244	0.01	0.01	120	121
solder	non noble metal	tin	7440-31-5	0.049			24	
	noble metal	silver	7440-22-4	0.061			30	
	non noble metal	lead	7439-92-1	2.320	0.11	0.11	1140	1194
heatspreader	inorganic material	phosphorus	7723-14-0	0.177	0.01		87	
	non noble metal	iron	7439-89-6	0.590	0.03		290	
	non noble metal	copper	7440-50-8	589.466	28.95	28.99	289534	289911
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 Neubiberg
Internet	www.infineon.com